

In the Claims:

Please cancel claims 1-9, 20, and 23-34. Please amend claim 10. Please add new claims 35-40. The claims are as follows.

1-9 (Canceled)

10. (Currently amended) A method of forming an electronic package, comprising the steps of:

providing an electronic component having a first featurized surface and a second surface;
and

removing a portion of the second surface such that the second surface is substantially arcuate, ~~having a thickness greatest substantially near the center of the electronic component~~
wherein a distance between the first surface and the second surface continuously increases from a periphery of the electronic component to near a center of the electronic component.

11. (Original) The method of claim 10, further comprising the steps of:

electrically mounting the first featurized surface of the electronic component to a substrate; and

mounting an element to the second surface of the electronic component.

12. (Original) The method of claim 10, further comprising the step of:

removing at least one edge from a portion of the electronic component.

13. (Original) The method of claim 11, wherein the substrate is a carrier.
14. (Original) The method of claim 11, wherein the element is a cover plate.
15. (Original) The method of claim 11, wherein the element is a heat sink.
16. (Original) The method of claim 11, wherein the element is mounted to the second surface of the electronic component using an adhesive.
17. (Original) The method of claim 16, wherein the adhesive is a thermally conductive reflowable material.
18. (Original) The method of claim 10, wherein the step of removing a portion of the second surface is performed using a profiling tool.
19. (Original) The method of claim 18, wherein the profiling tool has a concave profiling surface.
20. (Canceled)
21. (Original) A method of forming a chip, comprising the steps of:
providing an electronic component having a first featurized surface and a second planar

surface;

removing a first portion of the second planar surface forming a first arcuate surface; and

removing a second portion of the second planar surface forming a second arcuate surface.

22. (Original) The method of claim 21, further comprising the steps of:

profiling at least one edge of the electronic component.

23-34. (Canceled)

35. (New) The method of claim 21, wherein a distance between the first surface and the second surface continuously increases from a periphery of the electronic component to near a center of the electronic component.

36. (New) A method of forming an electronic package, comprising the steps of:

providing a substrate having an opening therein; and

forming an electronic component mounted within the opening of the substrate, the electronic component having a non-planar first surface and a second arcuate surface opposing the first surface and having a contour such that a distance between the first surface and the second arcuate surface continuously increases from a periphery of the electronic component to near a center of the electronic component.

37. (New) The method of claim 36, further comprising mounting an element to the second

surface of the electronic component.

38. (New) The method of claim 37, wherein the element is a cover plate.

39. (New) The method of claim 37, wherein the element is a heat sink.

40. (New) The method of claim 37, wherein the element is mounted to the second surface of the electronic component using an adhesive.

41. (New) The method of claim 40, wherein the adhesive is a thermally conductive reflowable material.